JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO., LTD.

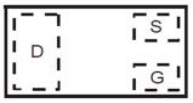
DFN1006-3L Plastic-Encapsulate MOSFETs

CJBA7002KL N-Channel MOSFET

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
60V	3.5Ω@10V	0.34A
	4.0Ω@4.5V	

DFN1006-3L

Bottom View



Top View
Internal Schematic

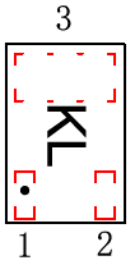
FEATURE

- High density cell design for Low $R_{DS(on)}$
- Voltage controlled small signal switch
- Rugged and reliable
- High saturation current capability
- ESD protected

APPLICATION

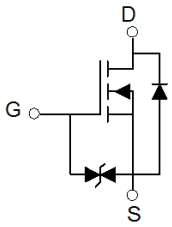
- Load Switch for Portable Devices
- DC/DC Converter

MARKING



Top View
KL=Device code
Solid dot = Pin 1 indicator

Equivalent Circuit



MOSFET MAXIMUM RATINGS (T_a=25℃ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current	I_D	0.34	A
Power Dissipation(note1)	P_D	275	mW
Thermal Resistance from Junction to Ambient(note1)	$R_{\theta JA}$	455	℃/W
Operation Junction and Storage Temperature Range	T_J,T_{STG}	-55~ +150	℃

MOSFET ELECTRICAL CHARACTERISTICS

MOSFET ELECTRICAL CHARACTERISTICS(T_a=25℃ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Static Characteristics						
Drain-Source Breakdown Voltage	V_{DS}	V_{GS} = 0V, I_D =250μA	60			V
Gate Threshold Voltage*	$V_{GS(th)}$	V_{DS} =V_{GS}, I_D =1mA	1	1.6	2.5	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} =48V,V_{GS} = 0V			1	μA
Gate –Source leakage current	I_{GSS1}	V_{GS} =±20V, V_{DS} = 0V			±10	μA
	I_{GSS2}	V_{GS} =±10V, V_{DS} = 0V			±200	nA
	I_{GSS3}	V_{GS} =±5V, V_{DS} = 0V			±100	nA
Drain-Source On-Resistance*	$R_{DS(on)}$	V_{GS} =10V,I_D =340mA			3.5	Ω
		V_{GS} = 4.5V, I_D =200mA			4	Ω
Diode Forward Voltage	V_{SD}	V_{GS}=0V, I_S=240mA			1.5	V
Recovered charge	Q_r	V_{GS}=0V,I_S=240mA,V_R=25V, dI_S/dt=-100A/μS		30		nC
Dynamic Characteristics**						
Input Capacitance	C_{iss}	V_{DS} =10V,V_{GS} =0V,f =1MHz			40	pF
Output Capacitance	C_{oss}				30	pF
Reverse Transfer Capacitance	C_{rss}				10	pF
Switching Characteristics**						
Turn-On Delay Time	$t_{d(on)}$	V_{GS}=10V,V_{DD}=50V,R_G=50Ω, R_{GS}=50Ω, R_L=250Ω			10	ns
Turn-Off Delay Time	$t_{d(off)}$				15	ns
Reverse recovery Time	t_{rr}	V_{GS}=0V,I_S=300mA,V_R=25V, dI_S/dt=-100A/μS		30		ns
GATE-SOURCE ZENER DIODE						
Gate-Source Breakdown Voltage	BV_{GSO}	I_{gs}=±1mA (Open Drain)	±21.5		±30	V

Notes :

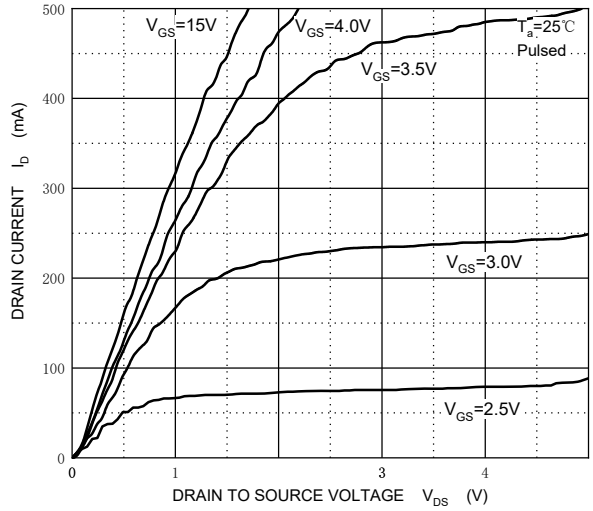
*Pulse Test : Pulse Width ≤300μs, Duty Cycle ≤2%.

**These parameters have no way to verify.

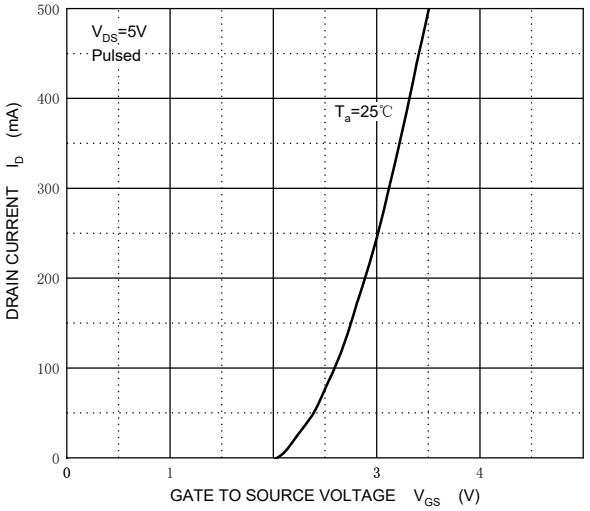
1.Surface mounted on FR4 board using 1 square inch pad size, 1oz copper.

Typical Characteristics

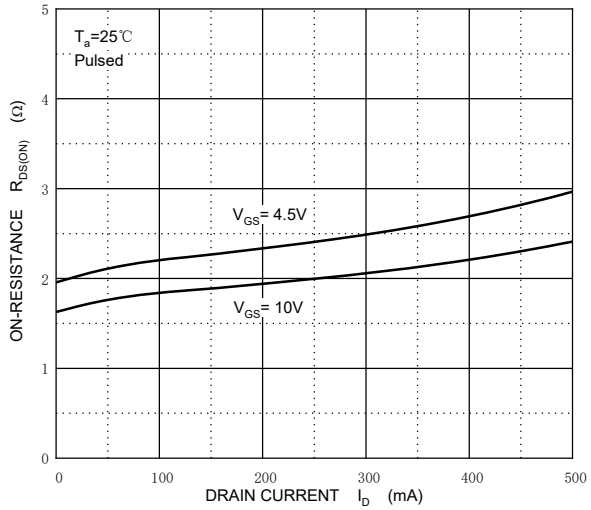
Output Characteristics



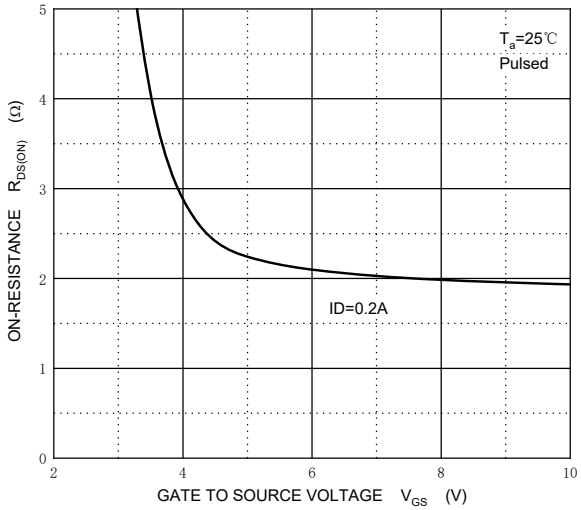
Transfer Characteristics



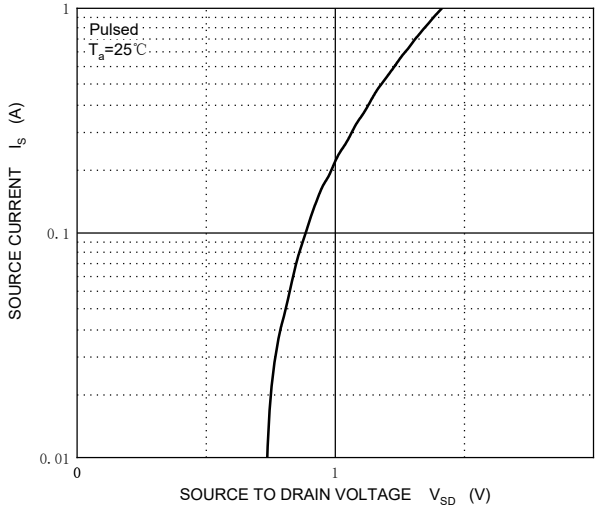
$R_{DS(ON)}$ —— I_D



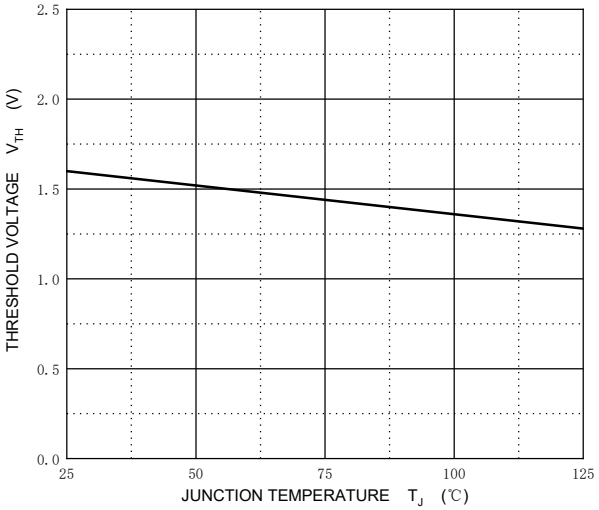
$R_{DS(ON)}$—— V_{GS}



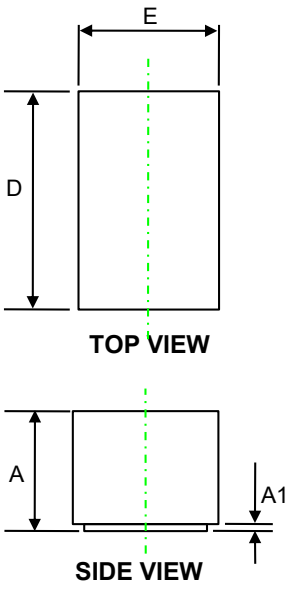
I_S —— V_{SD}

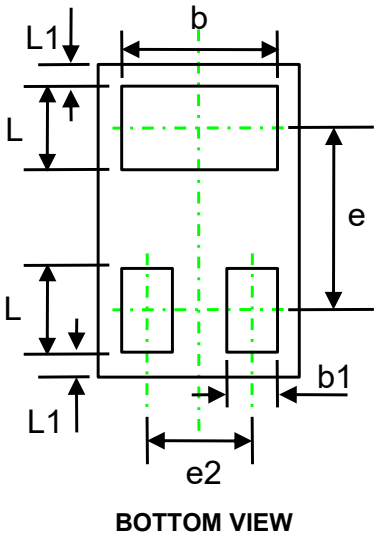


Threshold Voltage



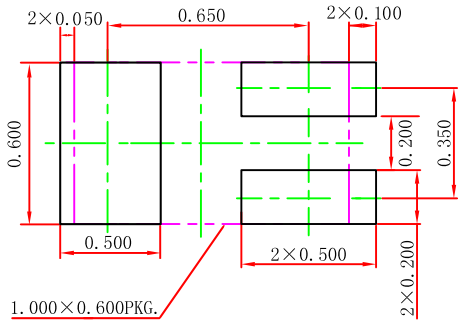
DFN1006-3L Package Outline Dimensions





Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.400	0.550	0.016	0.022
A1	0.000	0.050	0.000	0.002
D	0.950	1.050	0.037	0.041
E	0.550	0.650	0.022	0.026
b	0.450	0.550	0.018	0.022
e	0.650 REF.		0.026 REF.	
e2	0.350 REF.		0.014 REF.	
L1	0.050 REF.		0.002 REF.	
L	0.200	0.300	0.008	0.012
b1	0.100	0.200	0.004	0.008

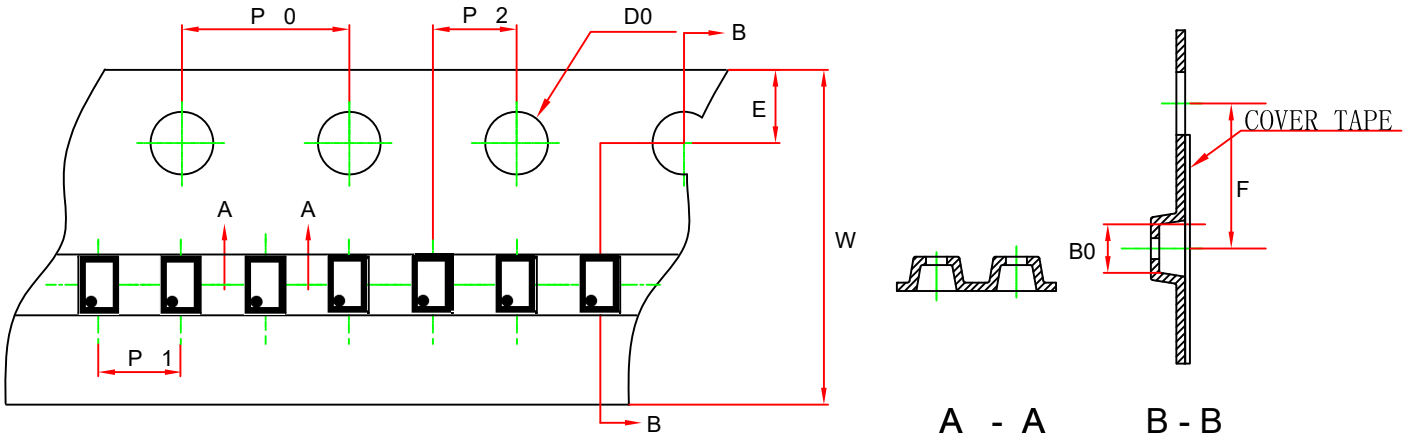
DFN1006-3L Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.050mm.
3.The pad layout is for reference purposes only.

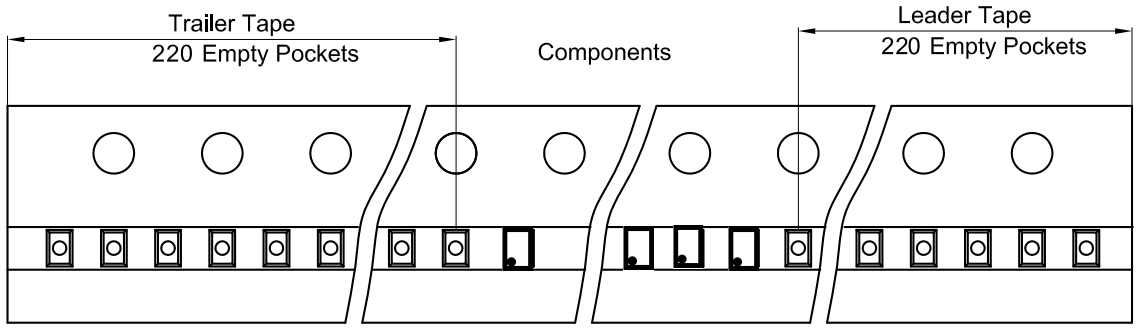
DFN1006-3L Tape and Reel

DFN1006-3L Embossed Carrier Tape

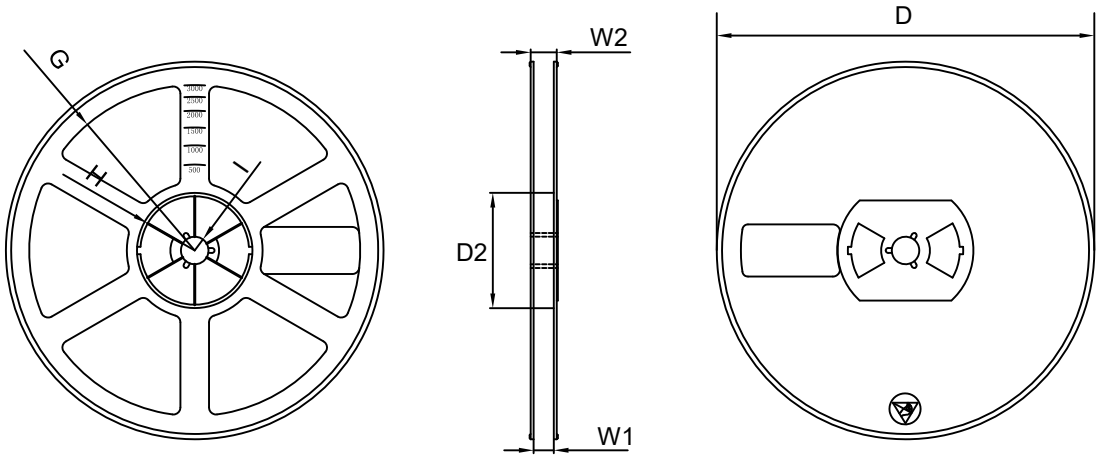


Dimensions In Millimeters (mm)								
Pkg type	B0	P0	P1	P2	E	F	W	D0
DFN1006-3L	1.11	4.00	2.00	2.00	1.75	3.50	8.00	1.55
Tolerance	+/-0.06	+/-0.1	+/-0.1	+/-0.1	+/-0.1	+/-0.1	+/-0.3	+/-0.1

DFN1006-3L Tape Leader and Trailer



DFN1006-3L Reel



Symbol	Dimensions In Millimeters (mm)						
	D	D2	G	H	I	W1	W2
7" Dia	Φ178.00	54.50	R78.00	R25.6	R6.5	9.50	12.30
Tolerance	+/-2	+/-1	+/-1	+/-1	+/-1	+/-2	+/-1.5

REEL	Reel Size	Box	Box size(mm)	Carton	Carton Size(mm)
10000 pcs	7 inch	150000 pcs	220×220×210	600000 pcs	450×450×240